

CONDUCTOR SUBSTRATE, SEMICONDUCTOR DEVICE
AND PRODUCTION METHOD THEREOF

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ABSTRACT OF THE DISCLOSURE

10 A conductor substrate for mounting a semiconductor
element, at least a portion thereof mounting the
semiconductor element being sealed with an insulating
resin, wherein an uppermost surface layer of the
conductor substrate comprises copper or an alloy thereof,
and the conductor substrate is partly or entirely covered
15 with a layer of copper oxide containing a hydroxide
formed upon the surface treatment of the conductor
substrate and a process of producing the conductor
substrate as well as a process for the production of a
semiconductor device using the conductor substrate.